



“Critical Materials for Device Driven Scaling”

by the Critical Materials Council and TECHCET

CMC Conference Agenda

Speaker Name, Topics or Titles of Presentations provided below. Official Titles of Presentations will be provided on or before April 25.

CMC Conference, Embassy Suites Hotel, Hillsboro, OR May 5-6, 2016

Day 1, 8:00 am, Featured Keynote Speaker:

Tim G. Hendry
 VP Technology & Manufacturing Group, Director, Fab Materials
 Intel Corporation

Day 1, Session I, 8:30 am

Global Strategic Initiatives [Supply Chain]

<i>The New Normal in the Global IC Fab Industry</i>	Gus Richard, Sr. Research Analyst - Northland Capital
<i>Materials Market Trends and Issues, including the China Supply Chain</i>	Lita Shon-Roy, President/CEO - TECHCET
Equipment Market Growth for CMP, Deposition, Etch & Lithography	Risto Puhakka, President - VLSI Research
<i>Sourcing of Rare Earths and Conflict Minerals for the semiconductor industry</i>	Keith Long, Chief Technologist - USGS

One additional presentation anticipated (see www.cmcfabs.org/seminars/ for weekly updates)

Day 1, Session II

Immediate Challenges of Materials & Manufacturing

<i>Device and Application Trends</i>	Jim Feldhan, President - SEMICO Research
<i>Gas Market Dynamics - Helium, Neon, NF3</i>	Bruce Adams, Sr. Technology Analyst - TECHCET
<i>CMP Efficiency, Waste Handling Issues</i>	Bassam Elkhatib - Texas Instruments
<i>POUP strategies for Critical Materials</i>	Rob Nine, Strategic Marketing - Pall Microelectronics Group
<i>Intel - Requirements and Challenges for Cleaning Chemicals - Jeff Hemphill</i>	Jeff. Hemphill, Sr. Materials Engineer - Intel Corp.

Not the Usual Round Table

Evening Reception: 5pm - 7pm

May 6 (Fri) - Day 2 (1/2 day)

- Session II, Immediate Challenges, continued -

<i>ALD Precursor Development Challenges for HVM</i>	Jean Marc Girard, Ph.D. - Air Liquide
<i>Low Temp Spatial ALD for Multiple Patterning Materials</i>	S.I. Lee, Ph.D., Chief Technical Officer - Veeco

May 6 (Fri) - Day 2 (1/2 day)

Session III: * Emerging Materials Challenges

<i>Packaging Materials -Future Challenges</i>	Jan Vardaman, President - TechSearch International
<i>The Future of Materials for Memory Applications</i>	John Smythe, Ph.D., Advanced Technology Lead DMTS - MICRON Technologies
<i>ALD/CVD Material & Equipment Market Trends</i>	Jonas Sundqvist, Sr. Technology Analyst - TECHCET
<i>Agony in New Material Introductions - Minimizing and Correlating Variabilities</i>	David Thompson, Ph.D., Director of Process Chemistry - Applied Materials
<i>Alternate III/V Channel Material Challenges</i>	Max Kelman, Ph.D., Sr. Technology Manager - Aixtron
<i>Challenges Implementing Carbon NanoTubes CMOS fab</i>	Rahul Sam, Ph.D., Materials Development - Nantero
<i>Low Temp Nitride Source & Handling Hydrazine for ALD</i>	Dan Alvarez, Ph.D., Chief Technical Officer - RASIRC

Panel Discussion & Wrap-Up, 11:45 – 12:30 pm